



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-70-3					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	80	40,000	200 °C + N2	0	0.00
HAST	55	5,000	130 °C, 85 % RH	0	0.00
Pressure Pot	55	5,800	121°, 15 PSIG	0	0.00
Solder Dunk	165	495	260 °C, 10 s	0	0.00
Solderability	20	480	883 M2003	0	0.00
Temp. Cycle	165	137,500	- 65 °C to 150 °C	0	0.00